

Transaction Information

Tool ID	FIB2103
Tool Status	Disconnected
Location	Malta, USA
Wafer Size	300 mm
Fab Section	Lab
Tool Available Date	2022-04-18

General Product Information

Vendor Supplier	FEI
Model	FEI ExSolve CLM next Gen
Vintage	2015
Serial No	9923535
Asset Description	FIB2103-T-MT
Software Version	NA
CIM	Factory Automation Available
Process	Cut samples from wafers in line

Hardware Configuration (Fab)

System Type	Description	Quantity	Status
Main System	FEI ExSolve G2 Full Wafer TEM Preparation System	1	
Handler System	Brooks Front End	1	
Factory Interface	SMIF	1	
Options System	Gas Injection System (GIS) Module, C-Dep (SEM), Ins-Dep (SEM), W-Dep (SEM), W-Dep, C-Dep	5	
Others			

Hardware Configuration (Subfab / Auxilliary Units)

Description	Quantity	Status
TMC Vibration Isolation Table, Edwards XDS35 Dry Pumps	3	

Missing/Faulty Parts / Accesories List

Description	Quantity
Front End Flash Drive Failure, tool is down	1

Tool Pictures

General

FEI ExSolve G2 Full Wafer TEM
Preparation System









5350 NE Dawson Creek Drive
Hillsboro, Oregon 97124 USA

Model:	EXSOLVE 2 WTP
Serial Number:	
Year of Manufacture:	
Voltage:	230 VAC, 1 Phase
Wiring Configuration:	2 Wire + Ground
Frequency:	50/60 Hz
Full Load:	11 A
Largest Load:	2 A
Input Breaker:	30 A
SCCR:	2000 A
Interrupting Capacity:	2000 A
Diagram Number:	1114837



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Additional Configuration Files